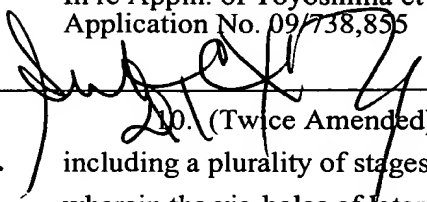



In re Appln. of Toyoshima et al.
Application No. 09/738,835


 10. (Twice Amended) The method of producing a multi-layered wiring board including a plurality of stages of via-holes formed by repeating the process of claim 1, wherein the via-holes of later-formed stages are smaller in size than the via-holes of earlier formed stages.